

# CMOS ASIC

T-90-60  
T-42-11-09

## CG10 Gate Array Device Description

Device Name	2-input Gate Equivalency <sup>1</sup>	Cell Propagation Delay	Maximum Number of Signal Pins <sup>2</sup>	I/O Options	Supply Voltage	Operating Temperature Range
CG10272	3,256 gates	0.5 ns (F/O = 2, 2-input NAND gate)	108	Input: Normal buffer Clock driver Schmitt trigger CMOS input Input pull-up/ pull-down  Output: Normal buffer 3-state Bidirectional Driver output Edge rate control	5 V ± 5%  Extended Voltage range of operation optional  Please contact Fujitsu	0 to 70°C  Extended temperature range optional  Please contact Fujitsu
CG10342	4,032 gates		123			
CG10492	5,572 gates		148			
CG10572	6,510 gates		163			
CG10692	7,684 gates		163			
CG10103	11,080 gates		188			
CG10133	14,720 gates		220			

<sup>1</sup>The gate counts in parentheses show the number of basic cells (BCs) on chip, including BCs used for I/O buffers. The UHB2 I/O buffers are implemented using basic cells.

<sup>2</sup>The maximum number of signal pins depends on the selected packages and output drive requirement.

<sup>3</sup>Design implementation dependent.

<sup>4</sup>Values for normal driver and clock buffer.

## CG10 Gate Array Package Options

Device Name	Dual In-line Package							Quad Flat Package									
	22	24	28	40	42	48	64	44	48	64	80	100	120	160	176	196	208
CG10272	P	P	P, P <sub>S</sub>	C, P	C, C <sub>S</sub> P, P <sub>S</sub>	C, P, P <sub>S</sub>	P <sub>S</sub>	P	C, P <sup>2</sup>	P	P	C, P	P				
CG10342		C, P	C, P	C, P	C <sub>S</sub> , P <sub>S</sub> P	C, P, P <sub>S</sub>	P <sub>S</sub>		C, P <sup>2</sup>	P	P	C, P	P				
CG10492		P	P	P	C, P, P <sub>S</sub>	C, P, P <sub>S</sub>	P <sub>S</sub>			P	P	P	P	P			
CG10572			P	P	P, P <sub>S</sub>	P, P <sub>S</sub>	P <sub>S</sub>			P	P	P	C, P	P			
CG10692				P	P, P <sub>S</sub>	P, P <sub>S</sub>	P <sub>S</sub>			P	P	P	C, P	P			
CG10103										P <sup>1</sup>	P <sup>1</sup>	P <sup>1</sup>	C, P	C, P	P <sup>1</sup>		
CG10133													P <sup>1</sup>	P <sup>1</sup>	P <sup>1</sup>	P <sup>1</sup>	P <sup>1</sup>

C = Ceramic Package

P = Plastic Package

C<sub>S</sub> = Ceramic shrink style package (DIP with pins spaced at 70 mils center to center; Quad flat packages with pins spaced at 20 mils center to center).

P<sub>S</sub> = Plastic shrink style package (DIP with pins spaced at 70 mils center to center).

<sup>1</sup>Under development.

<sup>2</sup>48-pin flat packages has two body size options

